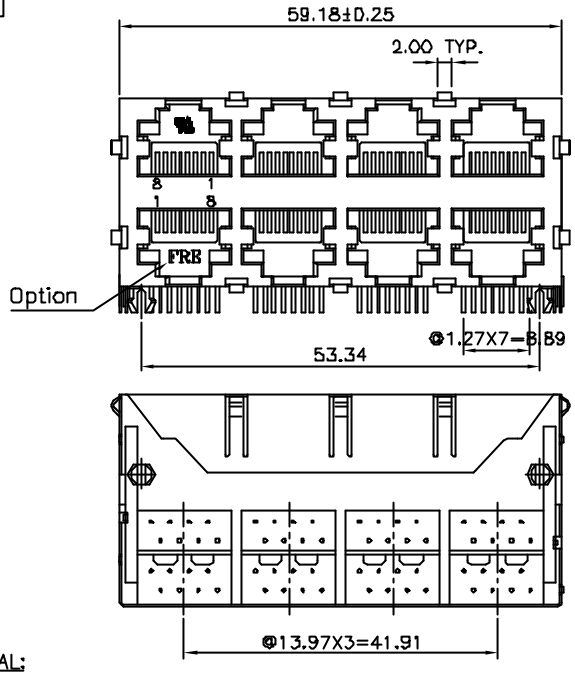
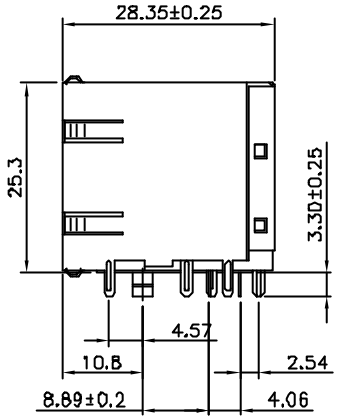
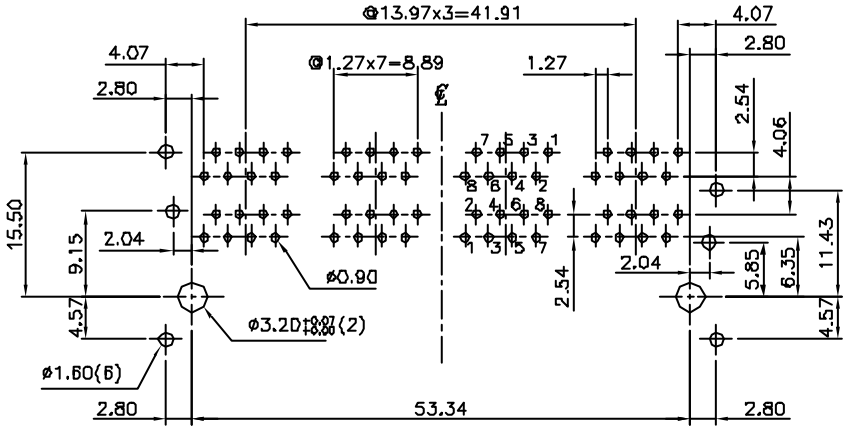
AIRFRD10







PC Board Layout Component Side Shown
PC Board Thickness=1.6mm

NOTES:

ELECTRICAL:
1. VOLTAGE RATING : 125 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 50 MILLIOHMS MAX.
4. INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
5. DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:
1. HOUSING MATERIAL : NYLON (FR52 OR PA9T) UL94V-0
2. INSERT MATERIAL : NYLON (FR52 OR PA9T) UL94V-0
3. CONTACT MATERIAL : PHOSPHOR BRONZE ø0.46mm.
4. PLATING : GOLD PLATING OVER NICKEL.
5. OPERATING LIFE : 750 CYCLES MIN.
6. PCB RETENTION PRE-SOLDER : 1 LB MIN.
7. PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:
1. STORAGE : -40°C TO +85°C.
2. OPERATION: -40°C TO +85°C.
3. WAVE SOLDERING TEMPERRATURE: 255~265°C(5~10 SECONDS)

MATES WITH MODULAR PLUG CONFORMING TO
FCC PART 68, SUBPART F.
CUL FILE NO. E163191

ROHS PART NUMBER: E590X-57CXXX-L

2-2C
4-4C △1
6-6C
8-8C

Gold Thickness:
1- 3u" 2- 6u" 3-15u"
4-30u" 5-50u"
F - Gold Flash (SHENZHEN LESS 1u")

13 : FRONT PEG 4.57 W/FRE&UL LOGO FR52
W1 : FRONT PEG 4.57 W/FRE LOGO PA9T △2
△3 1Q : FRONT PEG 4.57 W/FRE&UL LOGO FR52

ROHS PART NUMBER: E5908-58C1W2-L △6

REVISION RECORD

REV	ECO	DESCRIPTION	DRFT	CHKD
1		ADD P/N.	OSJ 5/05/05'	
2		MODIFY P/N	JANY 8/05/05'	
3		ADD P/N.	OSJ 8/20/05'	
4		MODIFY P/N	JASPER 8/29/05'	
5		MODIFY P/N	YAN 10/21/05'	
6		MODIFY P/N	Jasper 11/09/05'	

MM (INCH)	DFTD YAN	DATE 03/25/05'	FULL RISE ELECTRONIC CO., LTD
TOLERANCES EXCEPT AS NOTED	CHKD	DATE	
	MFG	DATE	TITLE RJ45 STACKED GANGED JACK, 2X4
MM .0 ±0.2 ± .00 ±0.16 ± .000 ±0.079 ±	APPVL 05000	DATE 11/10/05'	
ANGLES ± 0.5	MATERIAL :		DRAWING NO. GE593A50-LA / PART NO. SEE NOTE
	QT'Y :		SIZE A3 REV 6
THIRD ANGLE PROJECTION	FINISH :		
	SCALE : 1.5 : 1		DO NOT SCALE DRAWING SHEET 1 OF 1

DETACHED LISTS